



## HY30N03

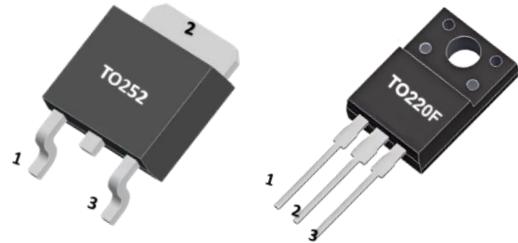
N-CHANNEL POWER MOSFET

### 30A, 30V N-CHANNEL ENHANCEMENT MODE POWER MOSFET

#### ■ DESCRIPTION

The HY30N03A uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

The HY30N03A meet the ROHS and Green Product requirement with full function reliability approved.



#### ■ FEATURE

- \* High density cell design for ultra low RDS(on)
- \* Fully characterized avalanche voltage and current
- \* Good stability and uniformity with high EAS
- \* Special process technology for high ESD capability
- \* Excellent package for good heat dissipation

#### ■ APPLICATIONS

- \* Hard switched and high frequency circuits
- \* Uninterruptible power supply
- \* Power switching application

#### ■ MARKING



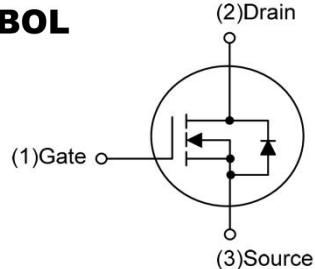
**HY** : HY LOGO

HY30N03A=Device Code

XXXX=Date Code

Solid Dot=Green molding compound

#### ■ SYMBOL



#### ■ ABSOLUTE MAXIMUM RATINGS(TA=25°C, unless otherwise specified.)

SYMBOL	PARAMETER	VALUE	UNIT
V <sub>DSS</sub>	Drain-Source Voltage	30	V
V <sub>GSS</sub>	Gate Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current	30	A
I <sub>DM</sub>	Pulsed Drain Current	40	A
E <sub>A</sub> S	Single Pulsed Avalanche Energy	90	mJ
P <sub>D</sub>	Maximum Power Dissipation	TO-220F	47
		TO-252	42
T <sub>J</sub>	Storage Temperature	150	°C
T <sub>STG</sub>	Thermal Resistance Fr .00m Junction To Ambient	-55~150	°C

Notes: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.



## HY30N03

N-CHANNEL POWER MOSFET

### ■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT		
Junction-to-Ambient	TO-220F	$R_{\theta JA}$	62.5	$^{\circ}\text{C}/\text{W}$		
	TO-252		110			
Junction-to-Case	TO-220F	$R_{\theta JC}$	2.66	$^{\circ}\text{C}/\text{W}$		
	TO-252		3.0			

### ■ ELECTRICAL CHARACTERISTICS (TA=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30			V
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
Drain-source on-state resistance (Note 2)	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=15\text{A}$		20	30	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=12.5\text{A}$		30	45	
Gate Threshold Voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	1.0			V
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}$ $f=1.0\text{MHz}$		1170		pF
Output Capacitance	$C_{\text{oss}}$			320		
Reverse Transfer Capacitance	$C_{\text{rss}}$			60		
<b>SWITCHING PARAMETERS</b>						
Total gate charge	$Q_{\text{g}}$	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=10\text{V}$ $I_{\text{D}}=30\text{A}$		18	35	nC
Gate-source charge	$Q_{\text{gs}}$			5.5		
Gate-drain charge	$Q_{\text{gd}}$			2		
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, R_{\text{L}}=0.5\Omega, I_{\text{D}}=30\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=7.5\Omega$		10	20	nS
Turn-On Rise time	$t_{\text{r}}$			10	20	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			25	40	
Turn-Off Fall time	$t_{\text{f}}$			15	30	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
Continuous drain-source diode forward current	$I_{\text{s}}$				30	A
Pulsed drain-source diode forward current	$I_{\text{SM}}$				40	A
Drain-source diode forward voltage	$V_{\text{SD}}$	$I_{\text{f}}=30\text{A}, V_{\text{GS}}=0\text{V}$		1.1	1.5	V
Reverse Recovery Time	$t_{\text{RR}}$	$I_{\text{f}}=30\text{A}, dI_{\text{f}}/dt=100\text{A}/\mu\text{s}$		50	100	ns

Notes:

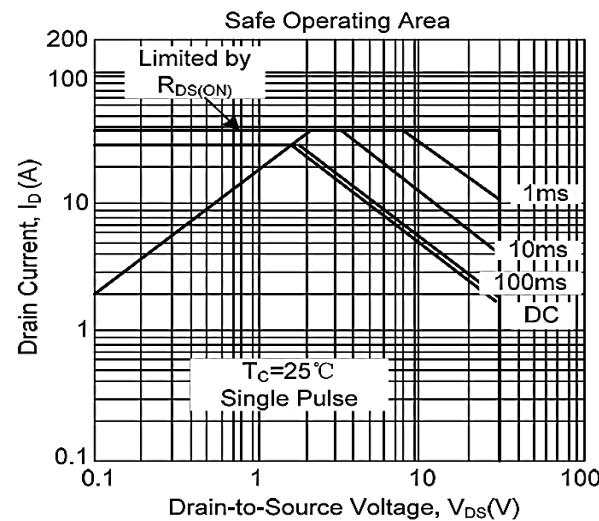
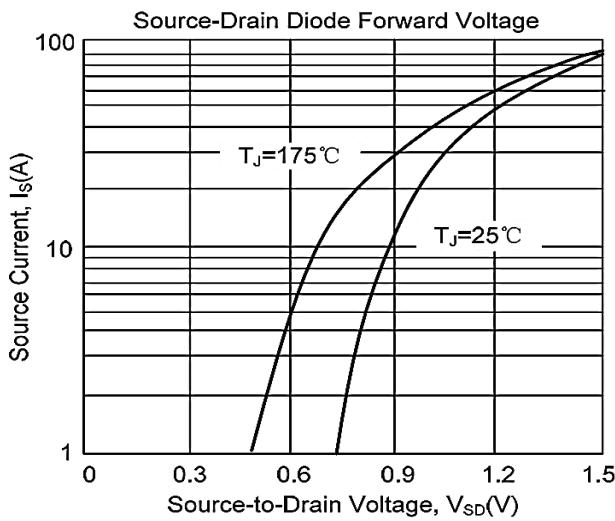
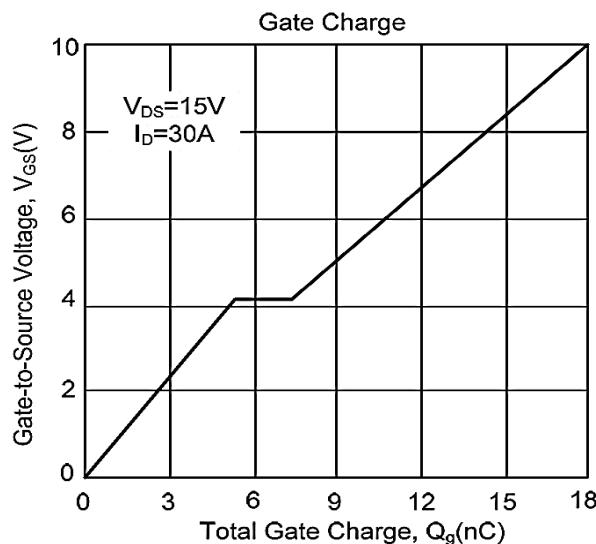
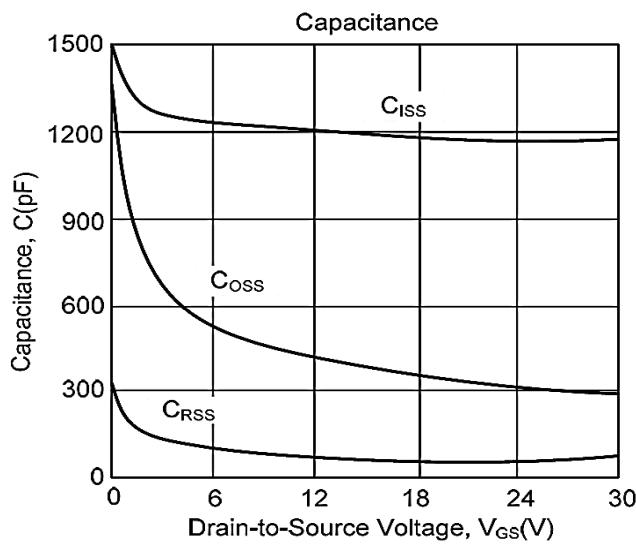
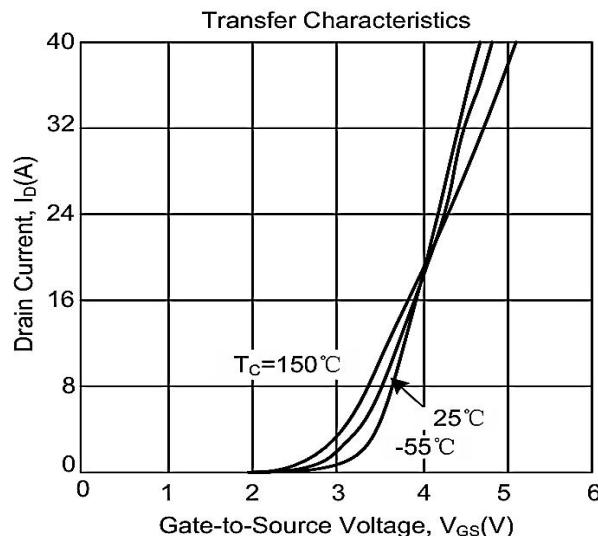
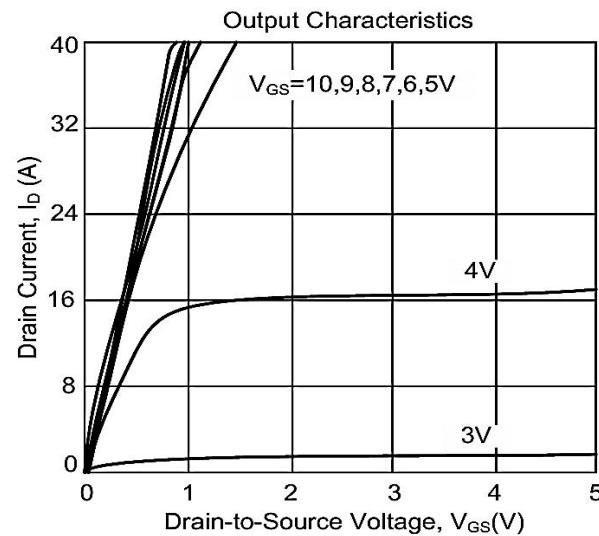
- Guaranteed by design, not subject to production testing.
- Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
- Essentially independent of operating temperature



## HY30N03

N-CHANNEL POWER MOSFET

### ■ TYPICAL CHARACTERISTICS

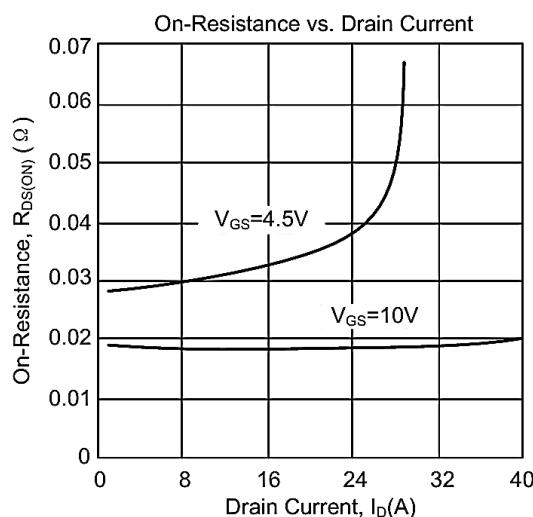
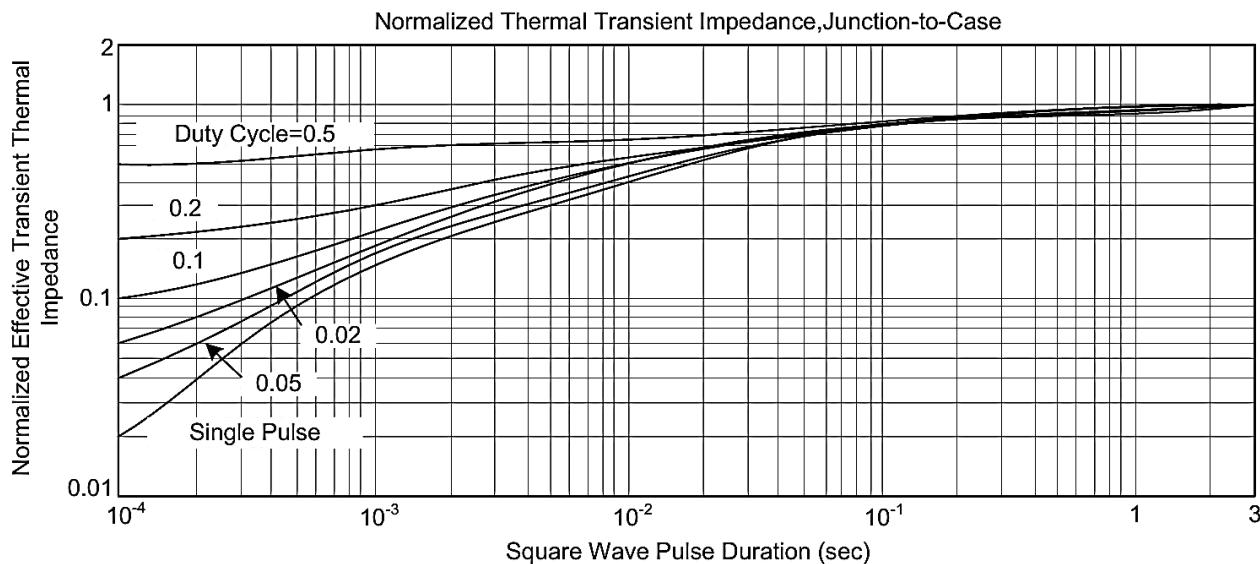




HY30N03

N-CHANNEL POWER MOSFET

## ■ TYPICAL CHARACTERISTICS(Con.t)

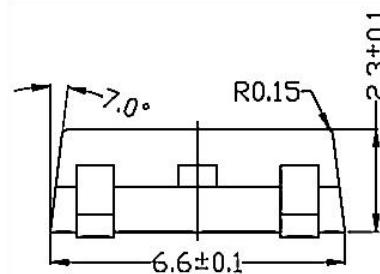
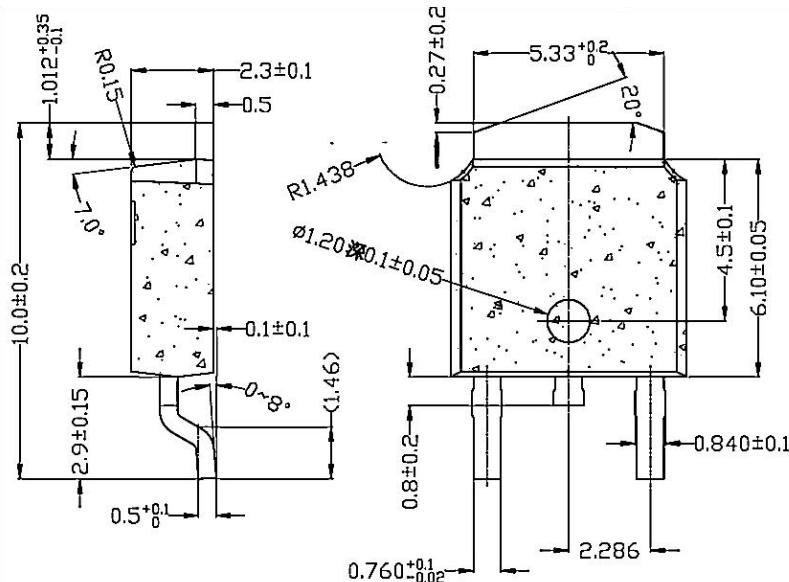




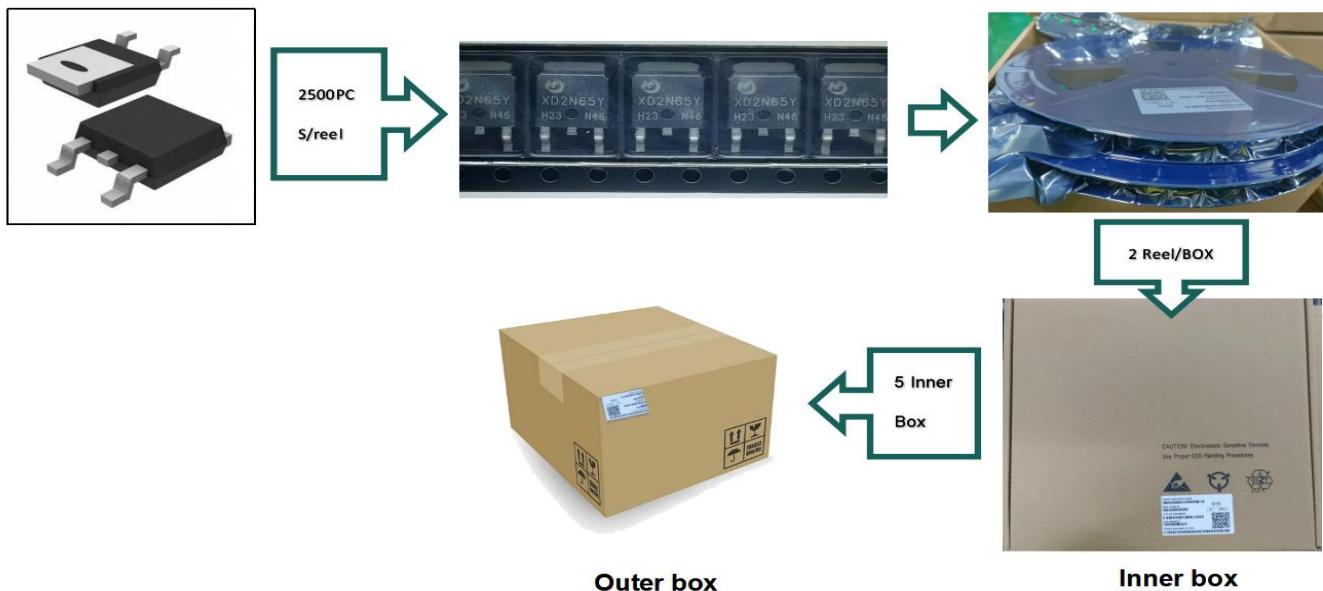
HY30N03

N-CHANNEL POWER MOSFET

### ■ TO - 252 PACKAGE OUTLINE DIMENSIONS



### ■ TO - 252 PACKING INFORMATION



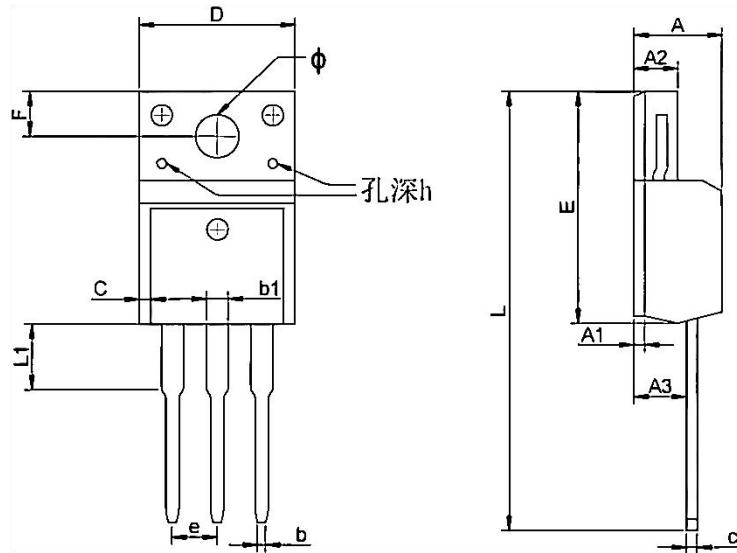
Package version	Reel dimensions $\Phi \times H$ (mm)	Per Reel (pcs)	Reels per box	Inner box dimensions L×W×H (mm)	Outer box (pcs)	Outer box dimensions L×W×H (mm)
TO-252	$\Phi 330 \times 20$	2500	2	360×340×50	25000	375×375×280



HY30N03

N-CHANNEL POWER MOSFET

### ■ TO- 220F PACKAGE OUTLINE DIMENSIONS

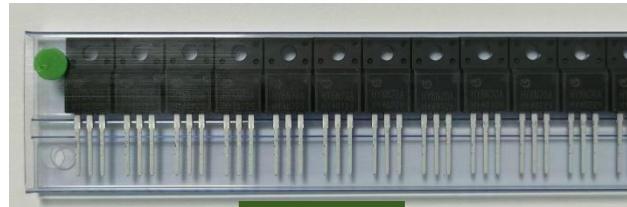


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max	Min	Max
A	4.300	4.750	0.169	0.185
A1	1.830	REF	0.072	REF
A2	2.300	2.850	0.090	0.112
A3	2.500	2.900	0.098	0.114
b	0.400	0.420	0.016	0.016
b1	1.220	1.280	0.048	0.050
C	0.690	0.720	0.027	0.028
c	0.490	0.510	0.019	0.020
D	9.960	10.200	0.392	0.400
E	15.000	15.950	0.588	0.625
e	2.574	TYP	0.101	TYP
F	3.470	REF	0.136	REF
y	3.200	REF	0.125	REF
h	0.000	0.300	0.000	0.012
L	28.780	28.900	1.128	1.133
L1	2.990	3.100	0.117	0.122

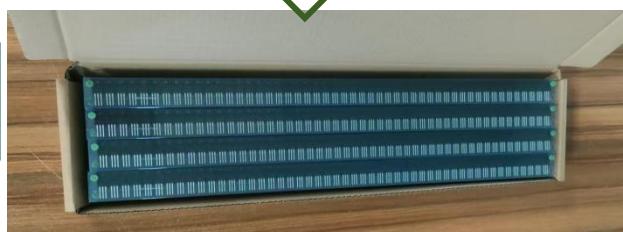
### ■ TO - 220F PACKING INFORMATION



50PCS



5 Inner Box



Outer Box

Inner Box

Package version	Tube dimensions LxWxH (mm)	Per Tube (pcs)	Tube per box	Inner box dimensions LxWxH (mm)	PCS/Inner box	Outer box dimensions LxWxH(mm)	PCS/Outer box
TO-220F	530*32*7	50	20	580*155*50	1000	602*277*188	5000